

Notes:

1.0 Orientations

- 1.1 Wafer surface is normal to a direction $127.85^\circ \pm 0.2^\circ$ rotated from the +Y through the +Z axis about the X axis.
- 1.2 Flats
 - 1.2.1 Primary flat is normal to the +X axis $\pm 0.2^\circ$.
 - 1.2.2 Secondary flat is 90° clockwise from the primary flat when viewing the polished face $\langle +Z/-Y \rangle$.

2.0 Edge

- 2.1 All edges rounded with $R0.27 \pm 0.05\text{mm}$.
- 2.2 No chips greater than 0.5mm in penetration and 1.0mm in length.

3.0 Surfaces

- 3.1 Side 1 $\langle +Z/-Y \rangle$ face
Polished 10-5 scratch-dig with 1mm edge exclusion. No pits or scratches visible with reflected light and unaided eye.
- 3.2 Side 2 $\langle +Y/-Z \rangle$ face
Ground, $R_a 0.50\mu\text{m}-0.70\mu\text{m}$.

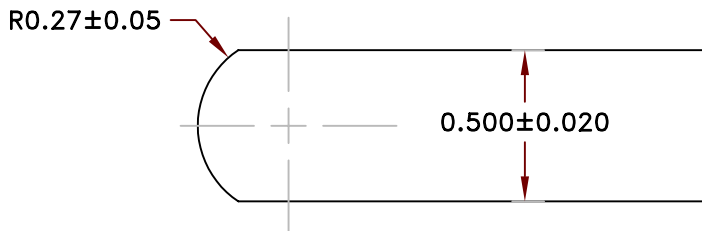
4.0 Flatness

- 4.1 Warp $< 50\mu\text{m}$.
- 4.2 TTV $< 25\mu\text{m}$.

5.0 Material

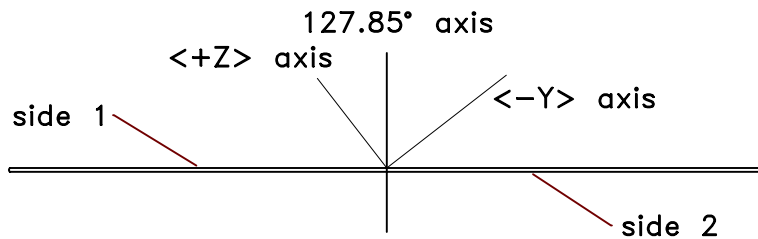
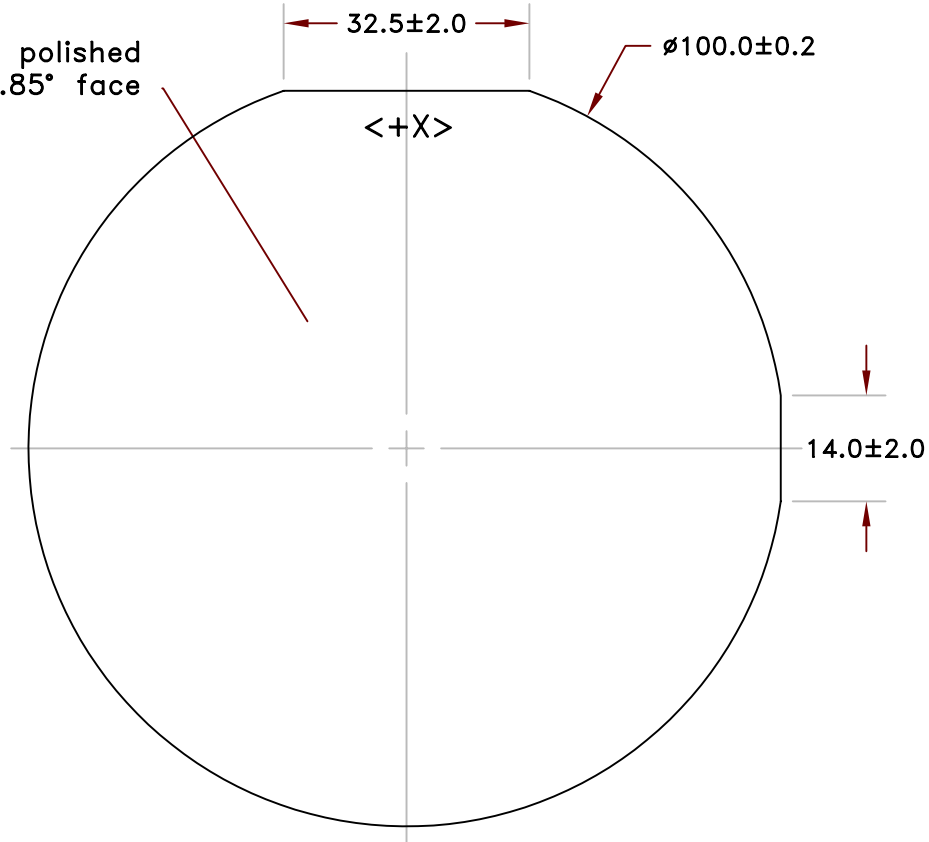
- 5.1 Curie temperature $1142.3 \pm 1.9^\circ\text{C}$

For Reference Only




Wafer Edge Detail, 40X

side 1 polished
 127.85° face



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Material: Lithium Niobate	DR. djundt	03-26-03	 Crystal Technology, Inc. An EPCOS Company
Unless otherwise specified, dimensions in mm	CHK.		
Tolerances			APPD.
Inches	Millimeters	Wafer Code:	Title:
.X ± 0.1	X ± 0.5	LNC128:100.050CP	LNR4 100 ϕ x 0.5mm, 128°
.XX ± 0.01	.X ± 0.25	Customer Approval:	Po/Gr, +X FLT, TTV < 25 μm
.XXX ± 0.005	.XX ± 0.1	Size: A	Dwg. No: 97-01064-01
.XXXX ± 0.0020	.XXX ± 0.05	Scale: 1:1	Rev: E
Angles ± 0.5°	DO NOT SCALE DRAWING		Sheet 1 of 1